

Custom Interconnects

Fuzz Button with Hardhat Test Socket/Interposer
1.00 mm pitch

Measurement and Model Results

prepared by

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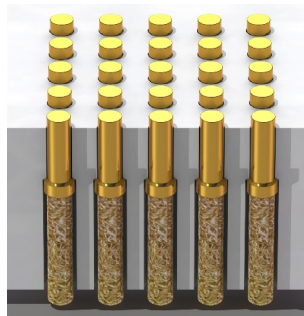
Objective

The objective of these measurements is to determine the RF performance of a Custom Interconnects Fuzz Button with Hardhat Test Socket/Interposer. For G-S-G configurations, a signal pin surrounded by grounded pins is selected for the signal transmission. For G-S-S-G configurations, two adjacent pins are used and all other pins are grounded. Measurements in both frequency and time domain form the basis for the evaluation. Parameters to be determined are pin capacitance and inductance of the signal pin, the mutual parameters, the propagation delay and the attenuation to 40 GHz.

Methodology

Capacitance and inductance for the equivalent circuits were determined through a combination of measurements in time and frequency domain. Frequency domain measurements were acquired with a network analyzer (Agilent HP8722C). The instrument was calibrated up to the end of the 0.022" diameter coax probes that are part of the test fixturing. The device under test (DUT) was then mounted to the fixture and the response measured from one side of the contact array. When the DUT pins terminate in an open circuit, a capacitance measurement results. When a short circuit compression plate is used, inductance can be determined.

Time domain measurements are obtained via Fourier transform from VNA tests. These measurements reveal the type of discontinuities at the interfaces plus contacts and establish bounds for digital system risetime and clock speeds.



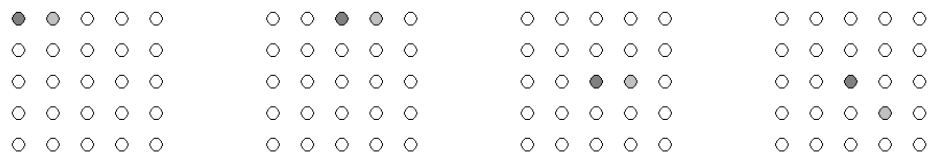
Cross-section of Socket/Interposer

Test procedures

To establish capacitance of the signal pin with respect to the rest of the array, a return loss calibration is performed. Phase angle information for S11 is selected and displayed. When the array is connected, a change of phase angle with frequency can be observed. It is recorded and will be used for determining the pin capacitance. The self-inductance of a pin is found in the same way, except the Fuzz Button with Hardhat Test Socket/Interposer contact array is compressed by a metal plate instead of an insulator. Thus a short circuit at the far end of the pin array results. Again, the analyzer is calibrated and S11 is recorded. The inductance of the connection can be derived from this measurement.

Setup

Testing was performed with a test setup that consists of a brass plate that contains the coaxial probes. The DUT is aligned and mounted to that plate. The opposite termination is also a metal plate with coaxial probes, albeit in the physical shape of an actual device to be tested or a flat plate with embedded coaxial probes. Measurements are performed for a corner pin of the contact array, a pin at the perimeter (edge) and one pin in the center (field), indicated in dark grey:



The second pin (light grey) is the second signal pin for G -S-S-G testing. Mutual parameters are also determined for the diagonal case. Configurations are referred to as G-S-G and G-S-S-G although strictly speaking this is not true. Signal pins are completely surrounded by ground pins since behavior would be very similar if they were connected to 50 Ohm driven pins as is the case in typical BGA/LGA environments.

True G-S-G and G-S-S-G configurations require linear arrays.

Figs. 1 and 2 show a typical arrangement base plate and DUT probe:

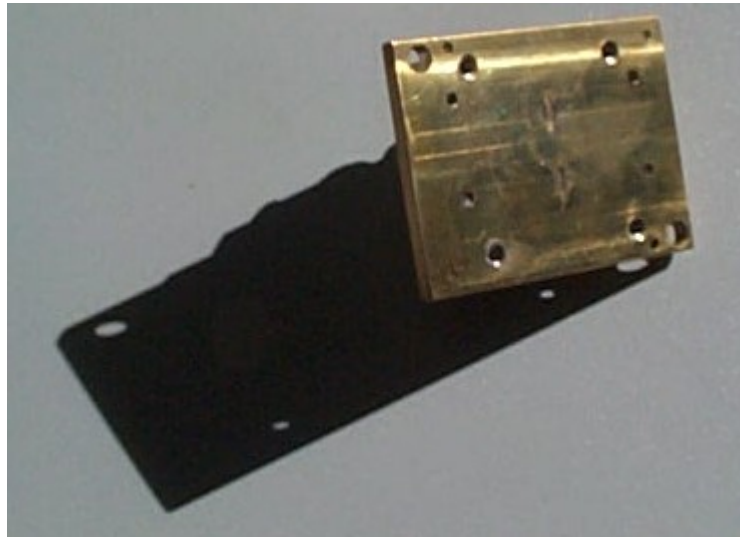


Figure 1 Fuzz Button Socket/Interposer base plate example



Figure 2 DUT plate

The Fuzz Button Socket/Interposer and base plate as well as the DUT plate are then mounted in a test fixture as shown in Fig. 3:

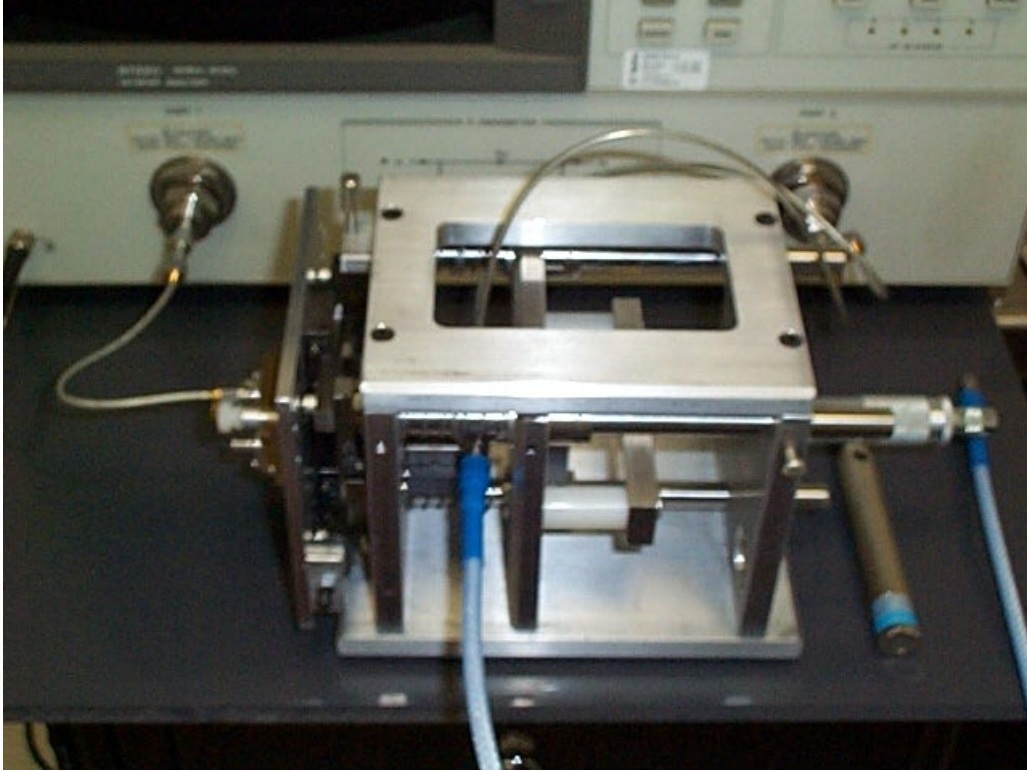


Figure 3 Test fixture

This fixture provides for independent X,Y and Z control of the components relative to each other. X, Y and angular alignment is established once at the beginning of a test series and then kept constant. Z (depth) alignment is measured via micrometer and is established according to specifications for the particular DUT.

Connections to the VNA are made with high quality coaxial cables with K connectors.

For G-S-G and G-S-S-G measurements, the ports are named as follows:

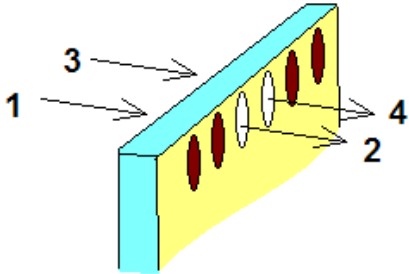
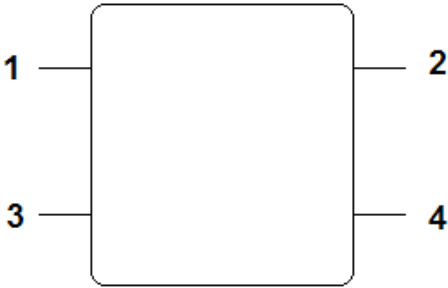
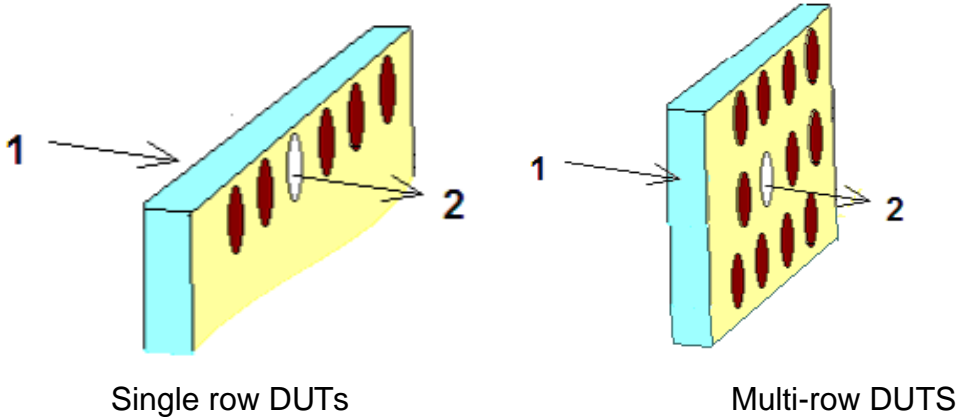


Figure 4 Ports for the G-S-G and G-S-S-G measurements

Signals are routed through two adjacent connections (light areas), unused connections are grounded (dark areas). The corresponding convention applies to the BGA/LGA array case.

Measurements G-S-G

Time domain

The time domain measurements will be presented first. TDR reflection measurements are shown below:

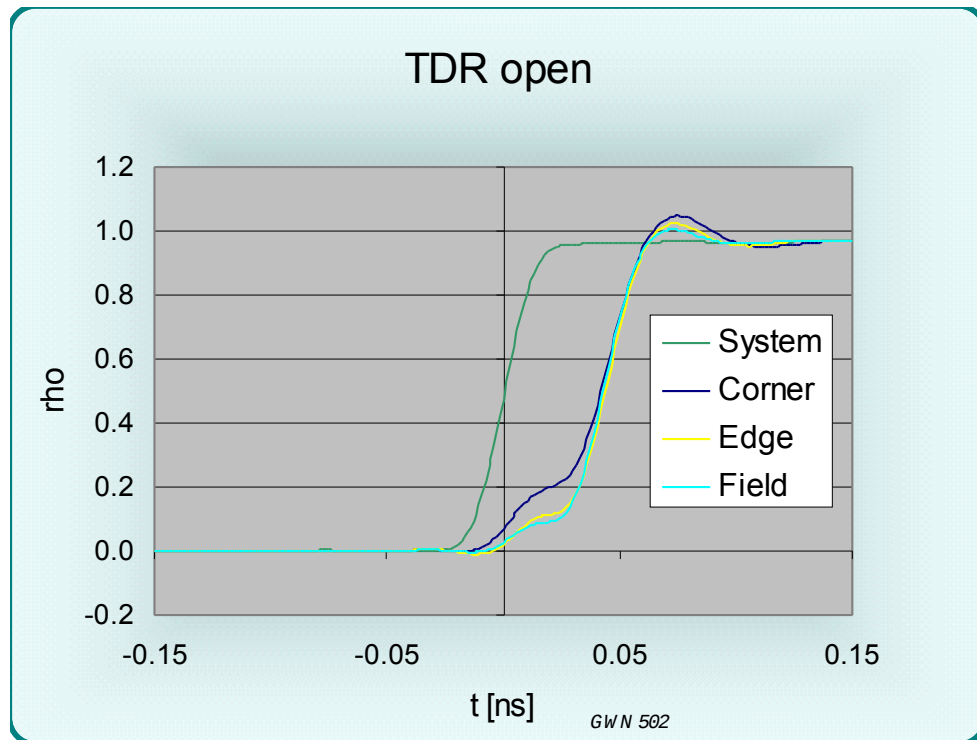


Figure 5 TDR signal from an OPEN circuited Fuzz Button Socket/Interposer

The reflected signals from the Fuzz Button Socket/Interposer (rightmost traces) show only a small deviation in shape from the original waveform (leftmost trace). The risetime is about 52.5, 43.5 and 33.0 ps for corner, edge and field, respectively and is noticeably larger than that of the system with the open probe (27.0 ps). Electrical pin length is about 20.3, 21.8 and 21.0 ps, respectively (one way).

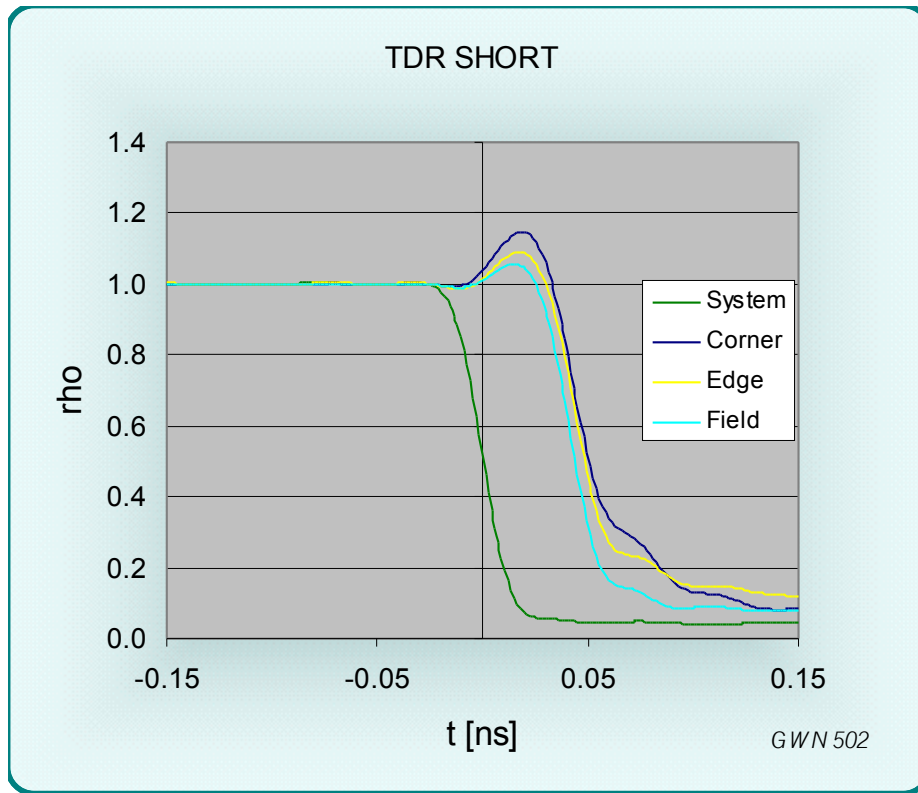


Figure 6 TDR signal from a SHORT circuited Fuzz Button Socket/Interposer

For the short circuited Fuzz Button Socket/Interposer the fall time is about 88.5, 111.0 and 52.5 ps for corner, edge and field, respectively. There is a noticeable increase over the system risetime of 28.5 ps caused by the contact impedance levels.

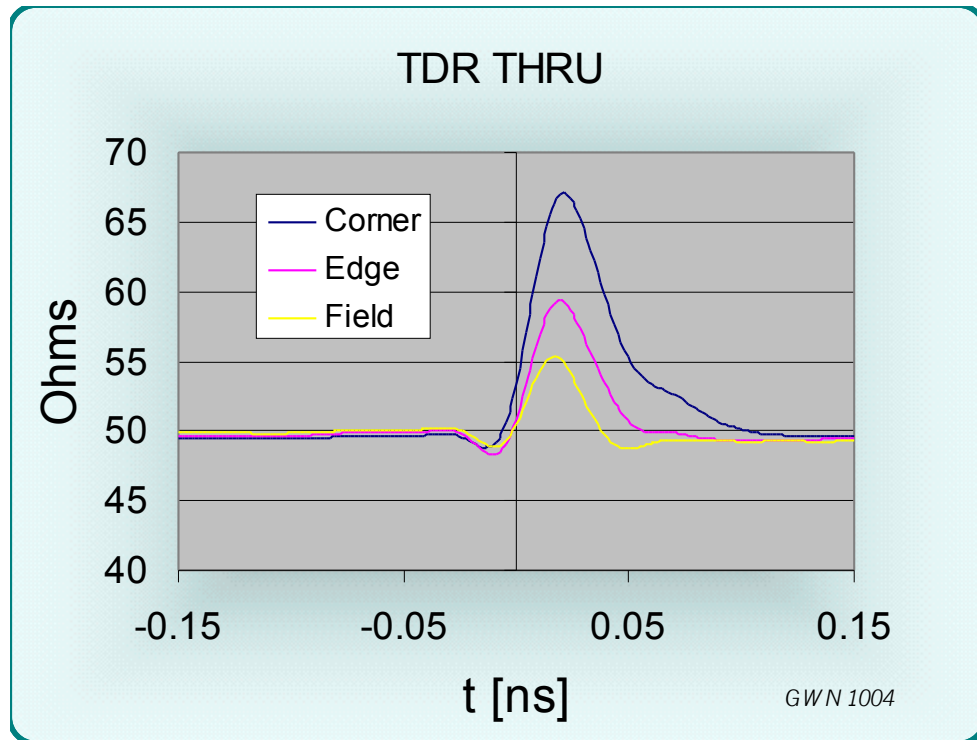


Figure 7 TDR measurement into a 50 Ohm probe

The thru TDR measurement shows an inductive response. The peaks correspond to an impedance of 67.1, 59.3 and 55.3 Ohms for corner, edge and field, respectively. It should be kept in mind that the impedance recorded here is not as high or as low as actually found in the specimen because of the risetime of the time step, in this case 25 ps. For connections with comparable or shorter electrical lengths this does not allow the peak to reach its full height.

The TDT performance for a step propagating through the contact arrangement was also recorded:

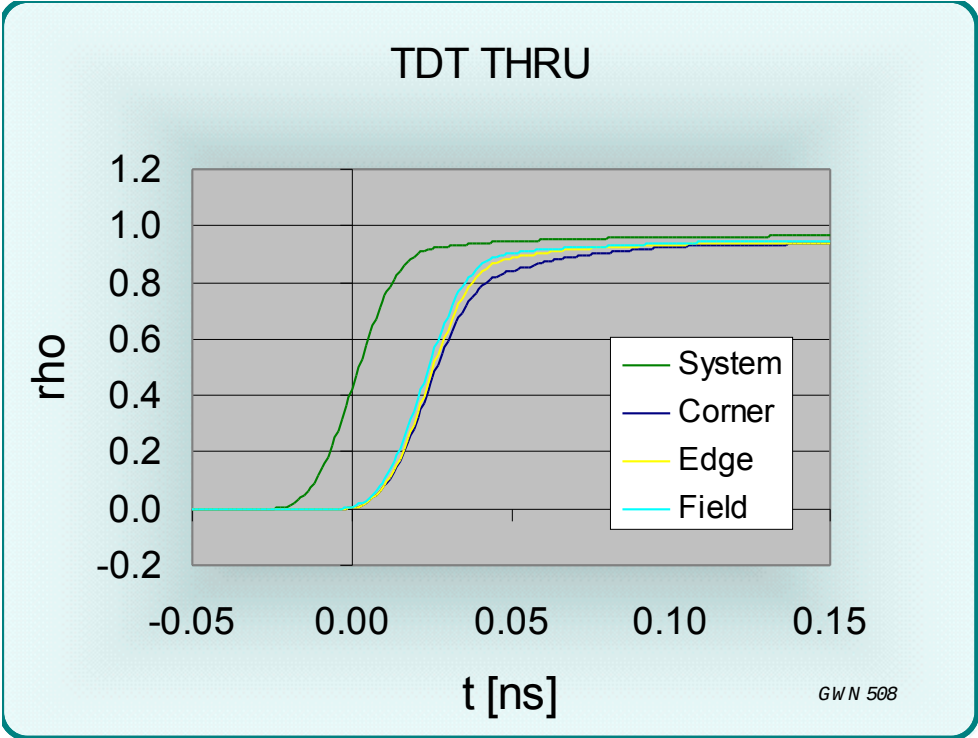


Figure 8 TDT measurement

The TDT measurements for transmission show a small contribution to risetime from the pin array (10-90% RT = 40.5, 31.5 and 30.0 ps for corner, edge and field, respectively, the system risetime is 28.5 ps). The added delay values at the 50% point are 23.9, 23.1 and 21.6 ps, respectively. There is no signal distortion. If the 20%-80% values are extracted, the risetimes are only 22.5, 19.5 and 19.5 ps, respectively vs. 18.0 ps system risetime.

Frequency domain

Network analyzer reflection measurements for a single sided drive of the signal pin with all other pins open circuited at the opposite end were performed to determine the pin capacitance. The analyzer was calibrated to the end of the probe and the phase of S11 was measured. From the curve the capacitance of the signal contact to ground can be determined (see Fig. 10).

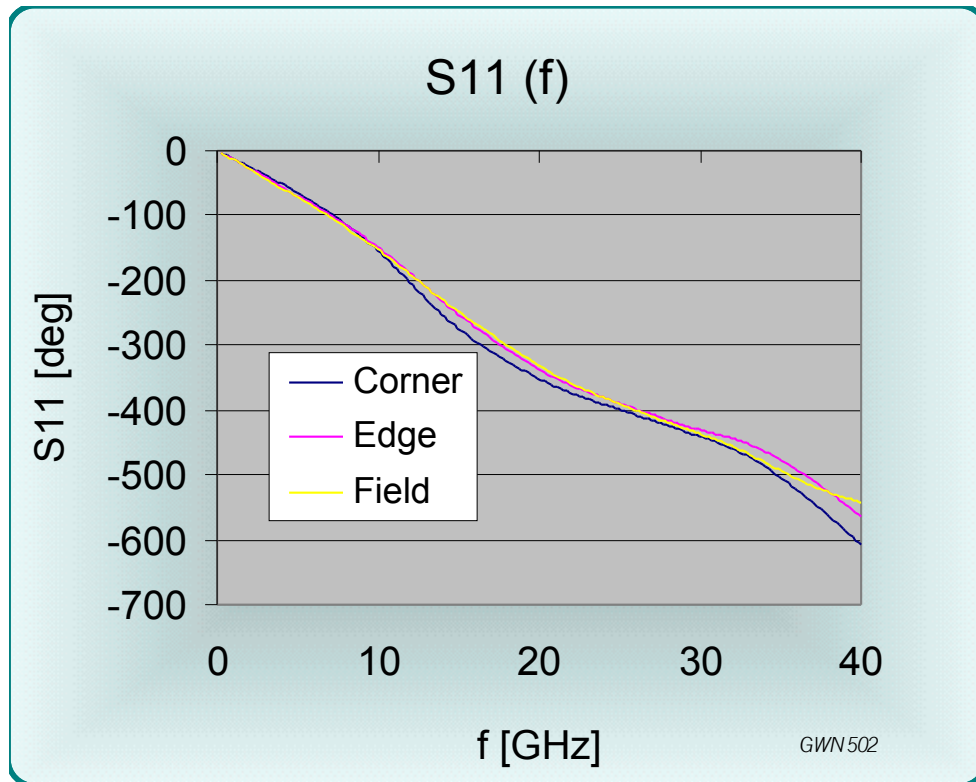


Figure 9 S11 phase (f) for the open circuited signal pin

There are no aberrations in the response.

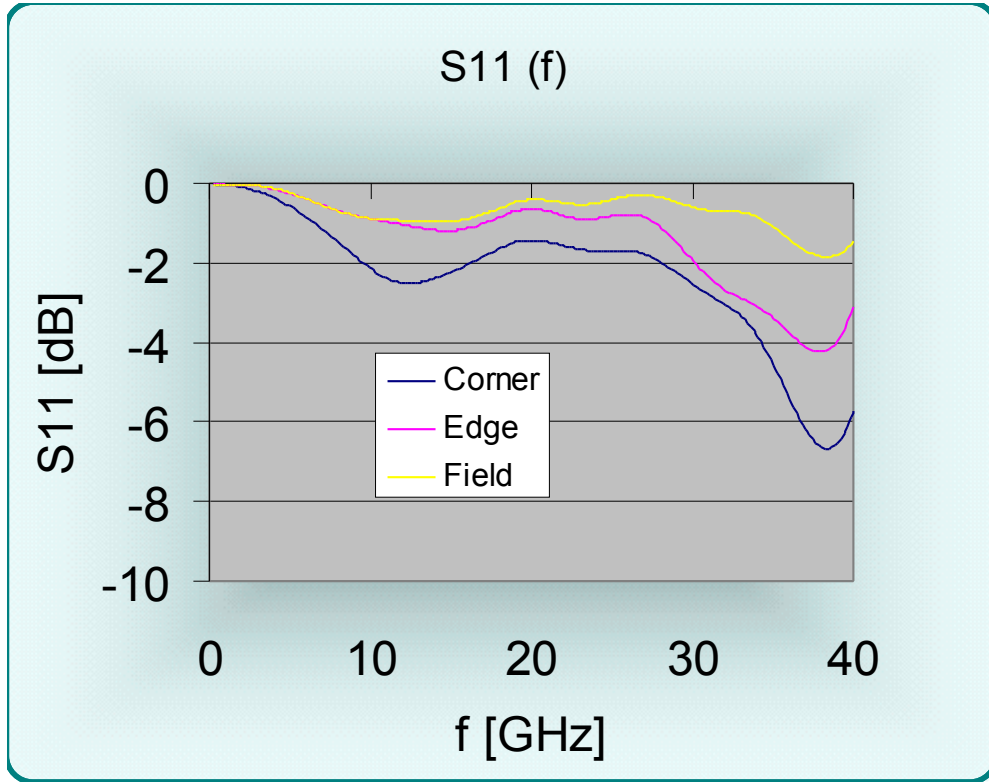


Figure 10 S11 magnitude (f) for the open circuited signal pin

While ideally the magnitude of S11 should be unity (0 dB), loss, radiation and resonances in the contact array are likely contributors to S11 (return loss) for the open circuited pins at elevated frequencies.

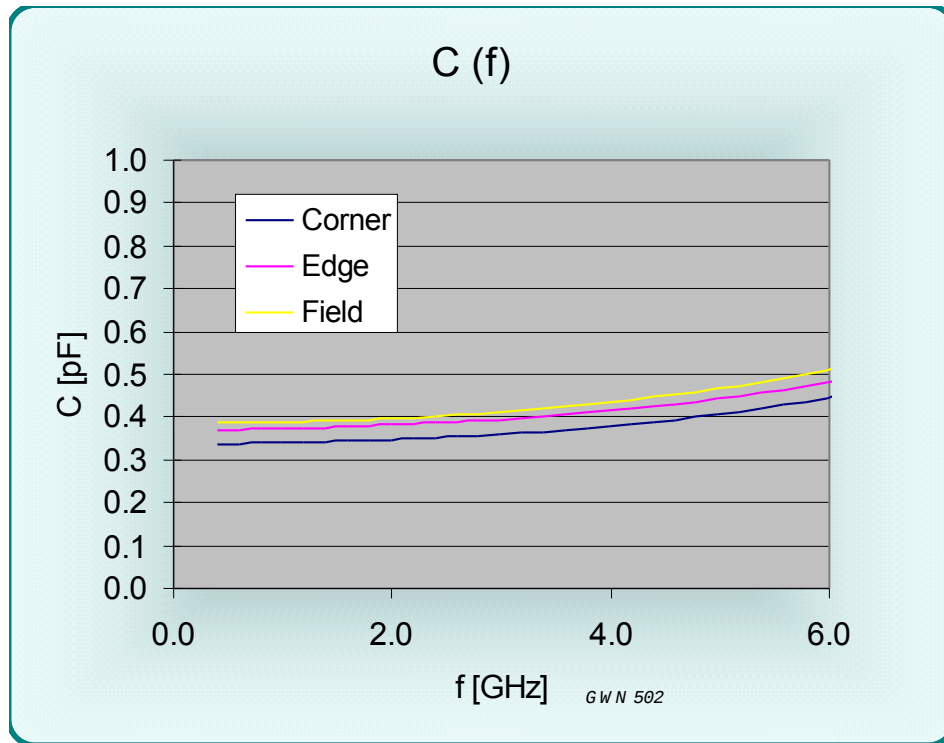


Figure 11 C(f) for the open circuited signal pin

Capacitance is 0.343, 0.377 and 0.392 pF for corner, edge and field, respectively, at low frequencies. The rise in capacitance toward 5 GHz is due to the fact that the pins form a transmission line with a length that has become a noticeable fraction of the signal wavelength. The lumped element representation of the transmission environment as a capacitor begins to become invalid at these frequencies and so does the mathematical calculation of capacitance from the measured parameters. This merely means the model of a lumped capacitor is not valid anymore. Instead, a transmission line model or a multi-section model must be applied beyond this frequency. As is evident from time domain and insertion loss measurements this does not imply that the DUT does not perform at these frequencies.

The Smith chart measurement for the open circuit shows no resonances. A small amount of loss is present.

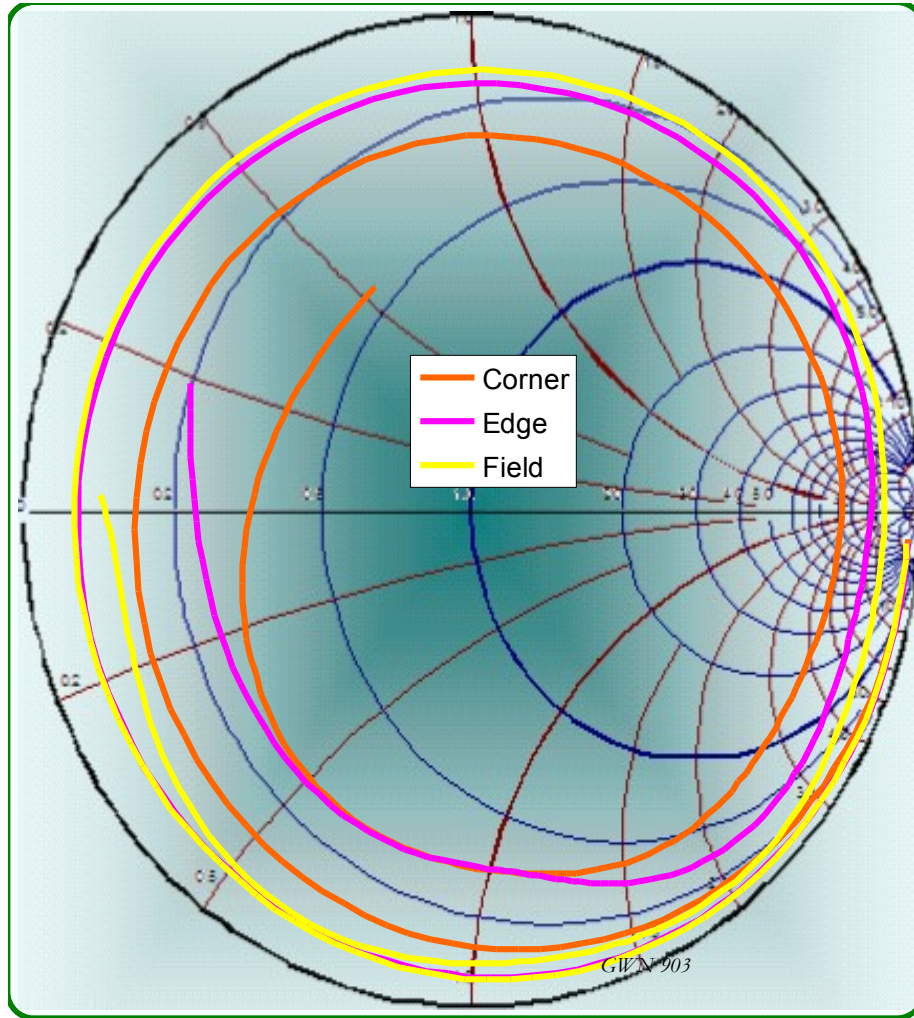


Figure 12 Reflections from the open circuited Fuzz Button Socket/Interposer

To extract pin inductance, the same types of measurements were performed with a shorted pin array. Shown below is the change in reflections from the Fuzz Button Socket/Interposer. Calibration was established with a short placed at the end of the coax probe.

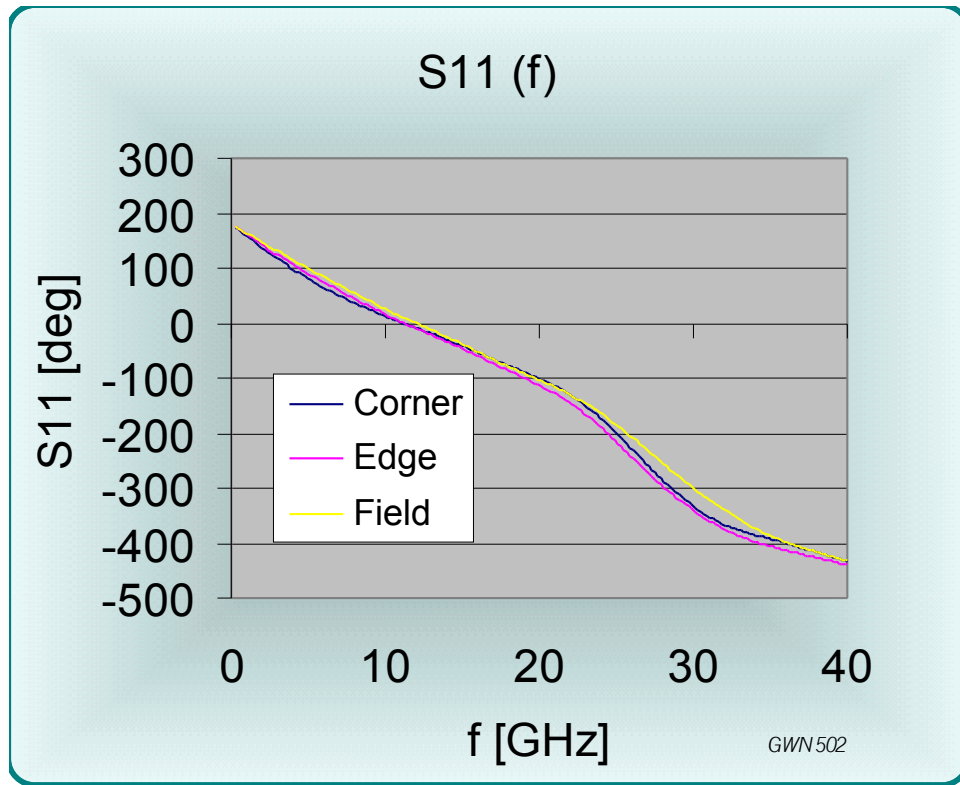


Figure 13 S11 phase (f) for the short circuited case

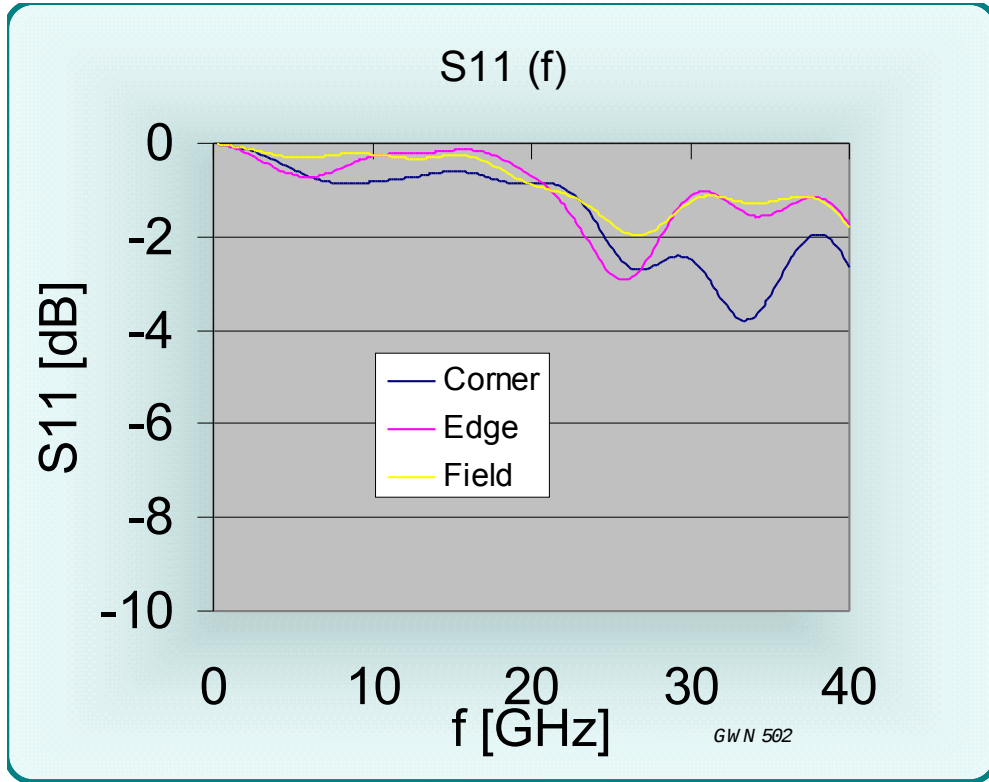


Figure 14 S11 magnitude (f) for the short circuited case

A small S11 return loss exists, likely the result of minimal loss and radiation.

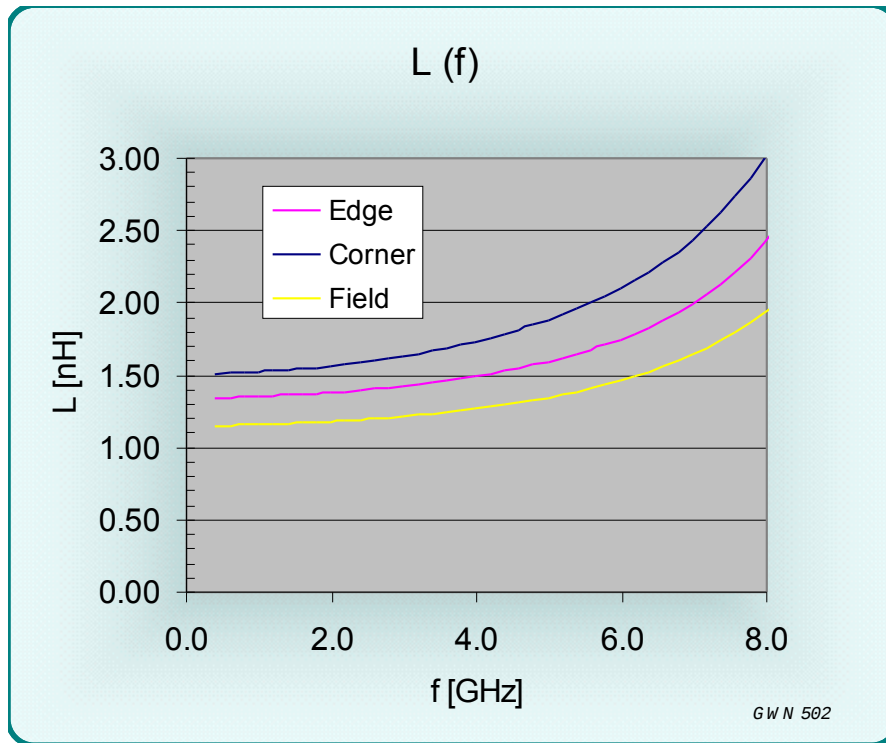


Figure 15 L(f) for the Fuzz Button Socket/Interposer

The phase change corresponds to an inductance of 1.54, 1.36 and 1.17 nH for corner, edge and field, respectively, at low frequencies. Toward 7 GHz inductance increases. At these frequencies, the transmission line nature of the arrangement must be taken into account and the simple lumped element value is no longer valid. This inductance is the loop inductance for the particular pitch and arrangement since self inductance is purely a mathematical construct and has little bearing on performance of the pin in the actual environment.

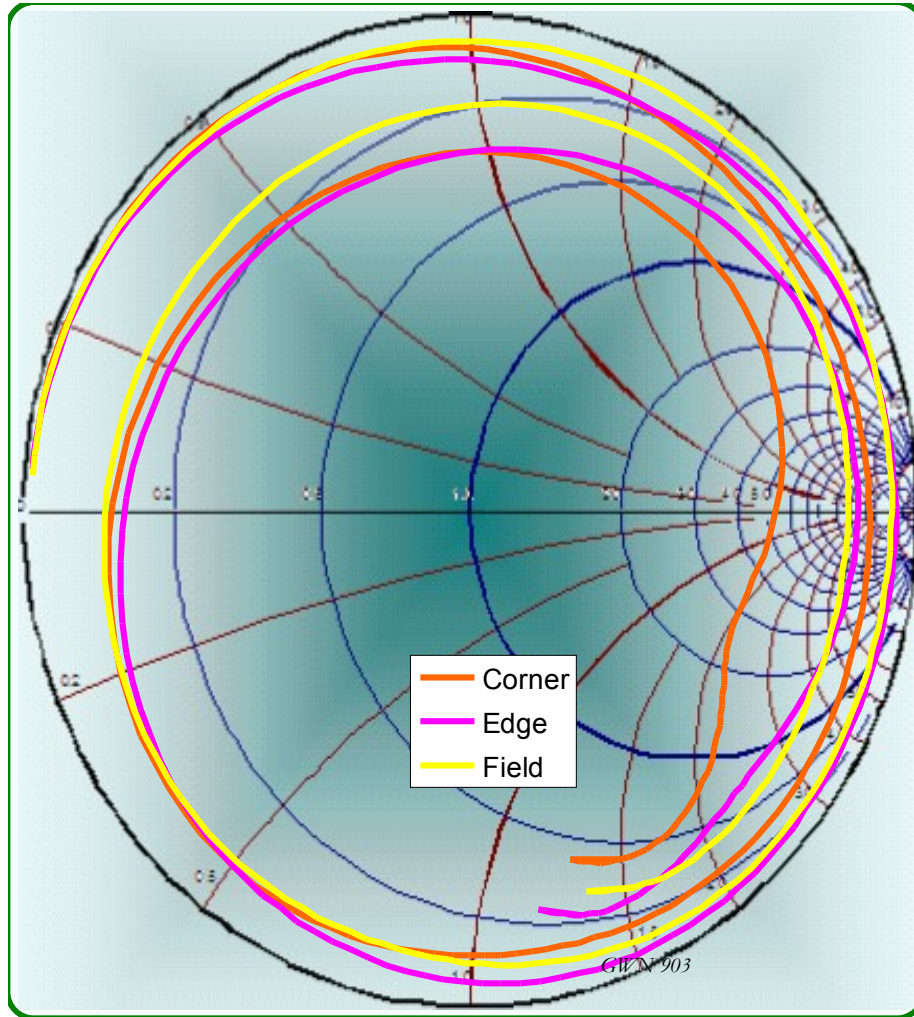


Figure 16 Short circuit response in the Smith chart

Only a small amount of loss is noticeable in the Smith chart for the short circuit condition.

An insertion loss measurement is shown below for the frequency range of 50 MHz to 40 GHz.

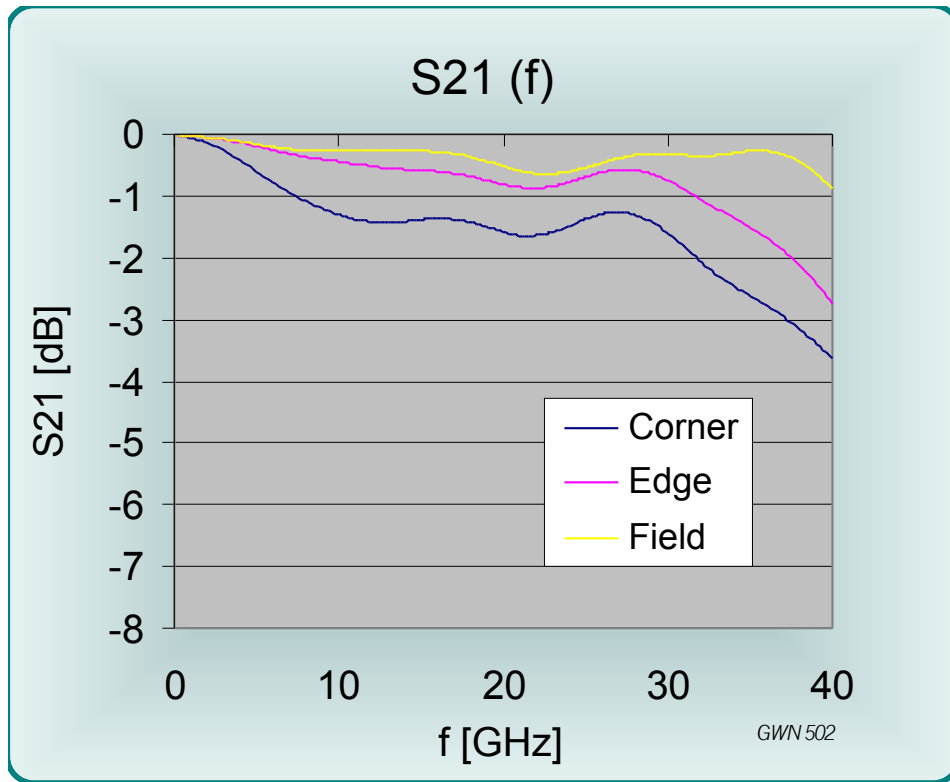


Figure 17 Insertion loss S21 (f)

Insertion loss is less than 1 dB to about 7.6, 31.9 and >40 GHz (corner, edge, field).
 The 3 dB point is not reached before 37.5, >40 and >40 GHz.

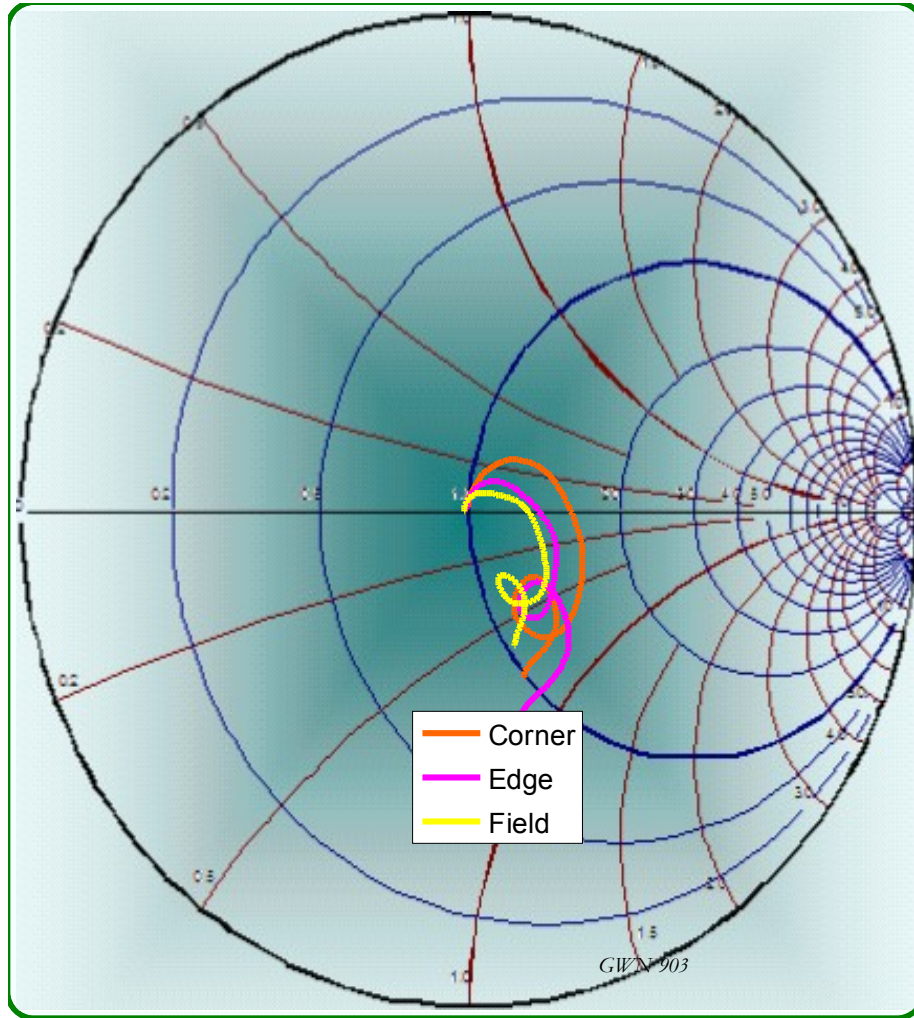


Figure 18 Smith chart for the thru measurement into a 50 Ohm probe

The Smith chart for thru measurements shows a good match at low frequencies. At higher frequencies reactive components become apparent.

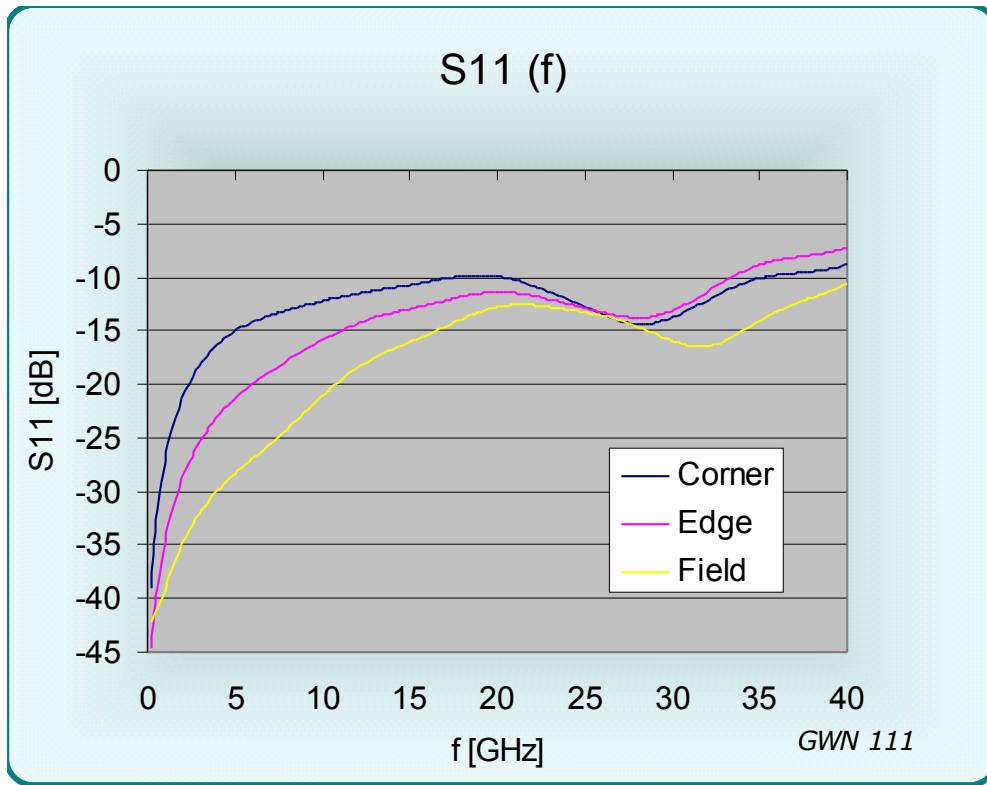


Figure 19 S11 magnitude (f) for the thru measurement into a 50 Ohm probe

Return loss reaches -20 dB at 2.4 GHz, 6.0 GHz and 10.8 GHz for corner, edge and field sites.

The level of the return loss for the thru measurement is lowest for the field configuration since its characteristic impedance is closest to 50 Ohms.

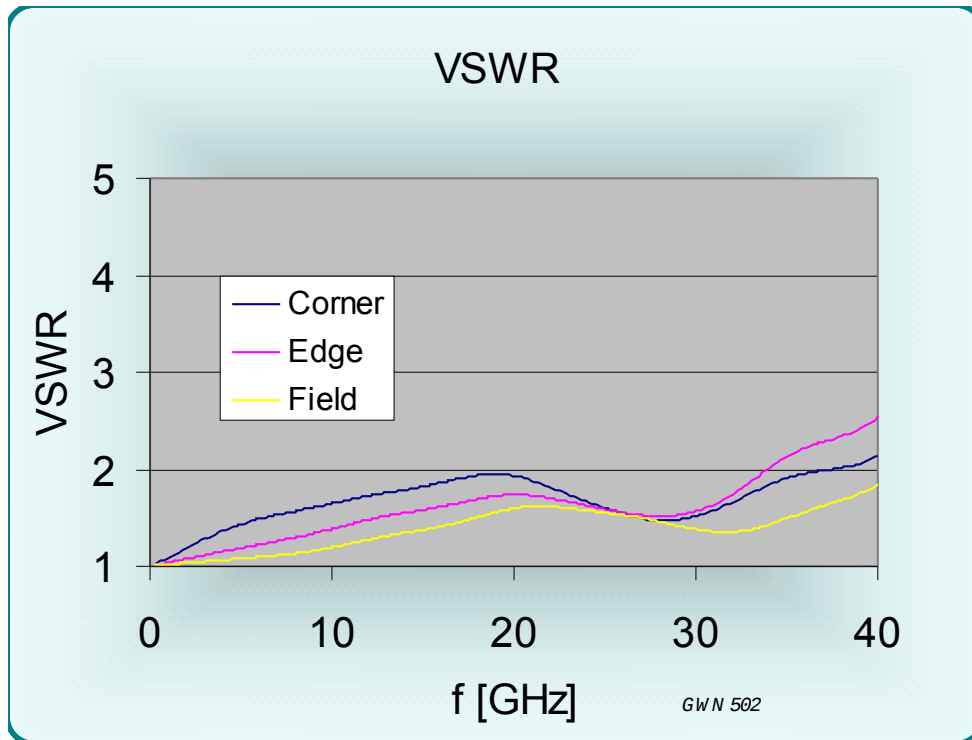


Figure 20 Standing wave ratio VSWR (f) [1 / div.]

The VSWR remains below 2 : 1 to a frequency of 37.5, 33.9 and >40 GHz (corner, edge, field).

Crosstalk was measured in the G-S-S-G configuration by feeding the signal pin and monitoring the response on an adjacent pin. Measurement results can be found in the section on the G-S-S-G configuration.

The mutual capacitance and inductance values will be extracted from G-S-S-G models and are also listed in that section.

Measurements G-S-S-G

Time domain

G-S-S-G transmission measurements were performed with a near symmetric 'field' configuration, mutual parameter determination was performed on all sites. Again, the time domain measurements will be presented first. A TDR reflection measurement is shown in Fig. 21 for the thru case at port 1 to port 2:

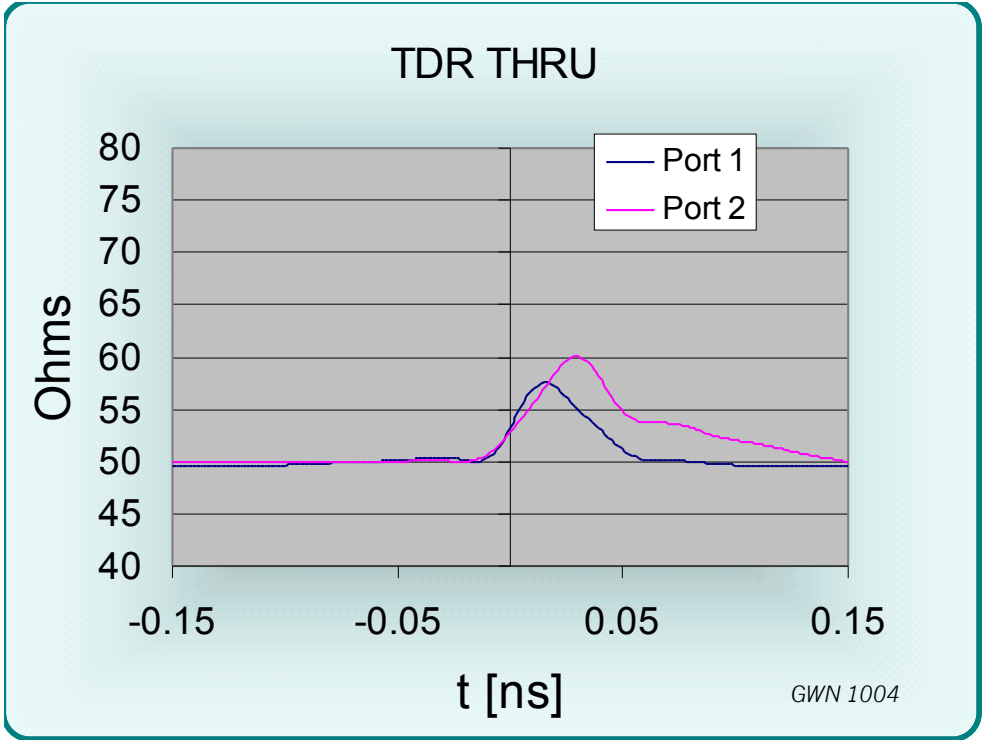


Figure 21 TDR through DUT into a terminated probe

The thru TDR measurement from port 1 to port 2 shows an inductive response. The low peak corresponds to a transmission line impedance of 57.6 Ohms. This is higher than in the G-S-G case since one of the adjacent pins is not grounded.

The TDT performance for a step propagating through the G-S-S-G pin arrangement was also recorded:

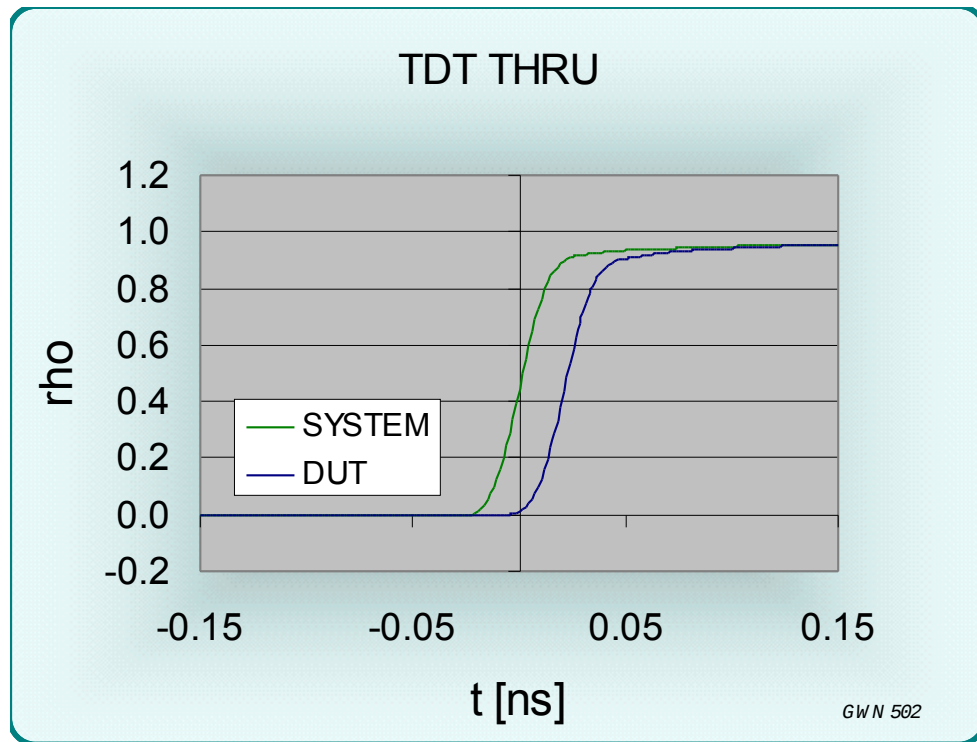


Figure 22 TDT measurement

The TDT measurements for transmission shows almost the same risetime from the pin array (10-90% RT = 30.0 ps) as the system risetime (28.5 ps). The added delay at the 50% point is 21.0 ps. The 20%-80% values are 19.5 ps and 18.0 ps, respectively.

Frequency domain

Network analyzer reflection measurements for the G-S-S-G case were taken with all except the pins under consideration terminated into 50 Ohms (ports 1-4). As a result, the scattering parameters shown below were recorded for reflection and transmission through the contact array.

First, an insertion loss measurement is shown for port 1 to port 2.

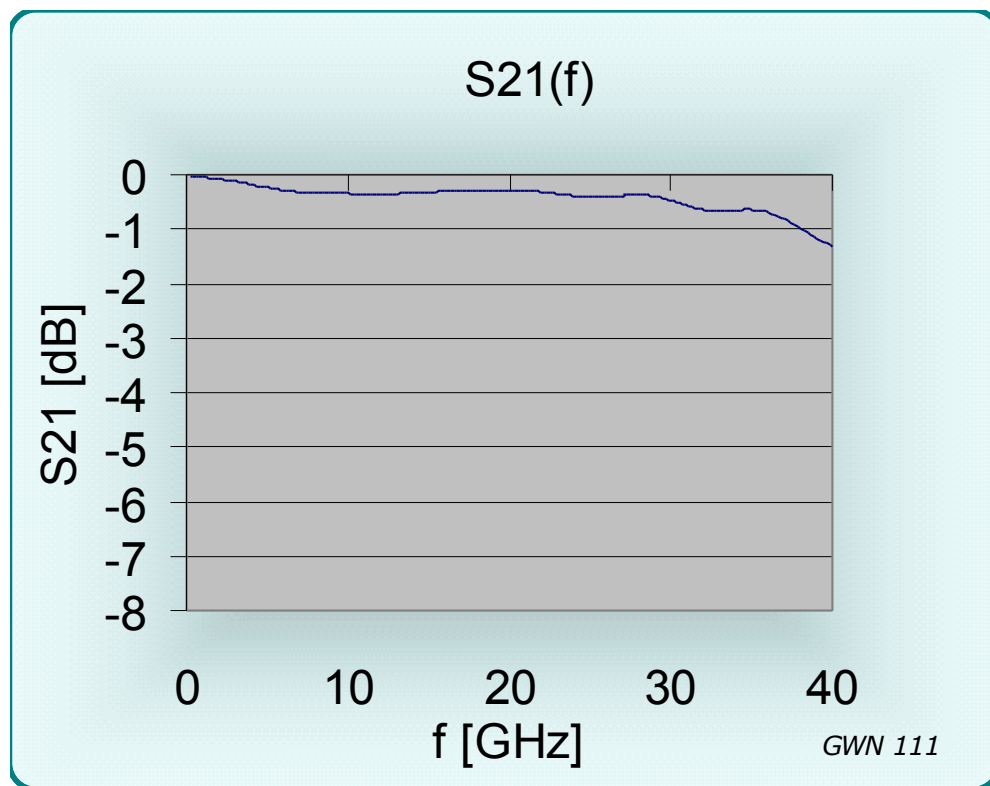


Figure 23 Insertion loss S21 (f)

Insertion loss is less than 1 dB to about 38.3 GHz.

Insertion loss is higher than in the G-S-G case because of the diversion of some signal energy from the thru connection to the adjacent second signal pin.

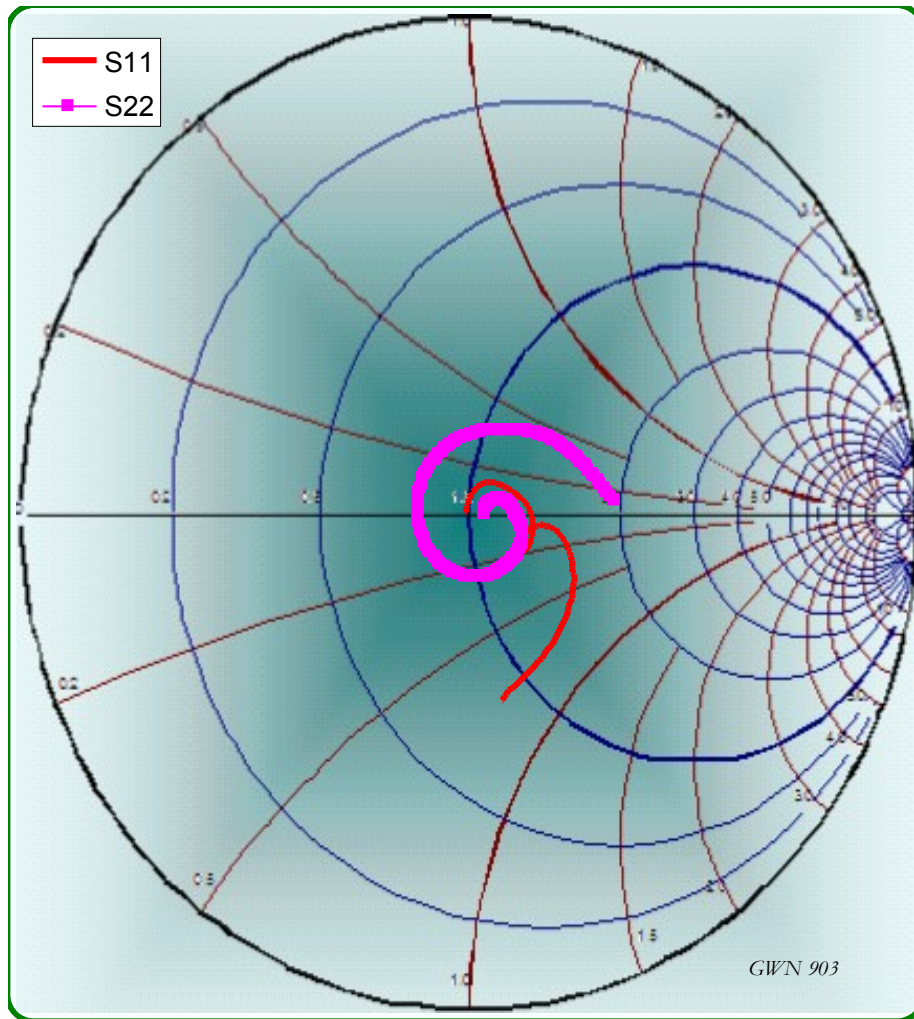


Figure 24 Smith chart for the thru measurement into a 50 Ohm probe

The Smith chart for the thru measurements shows a good match at low frequencies with some reactive components as frequency increases.

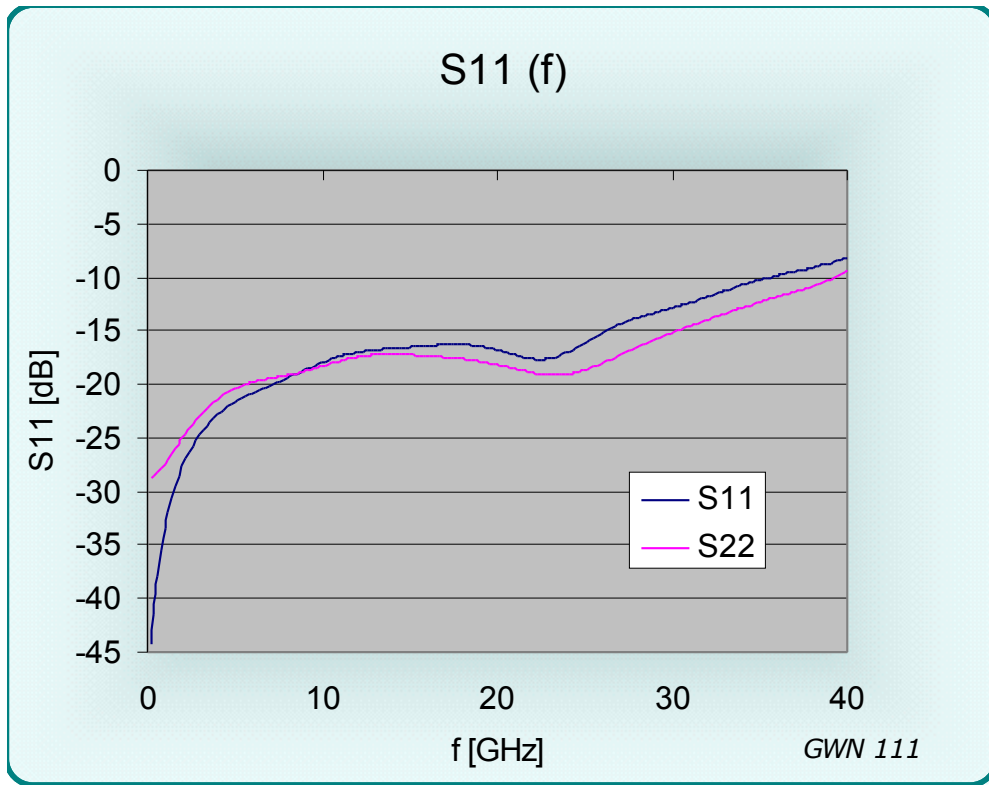


Figure 25 S11 magnitude (f) for the thru measurements into a 50 Ohm probe

The value of the return loss for the thru measurement reaches -20 dB at 7.4 GHz (S11) and 5.8 GHz (S22).

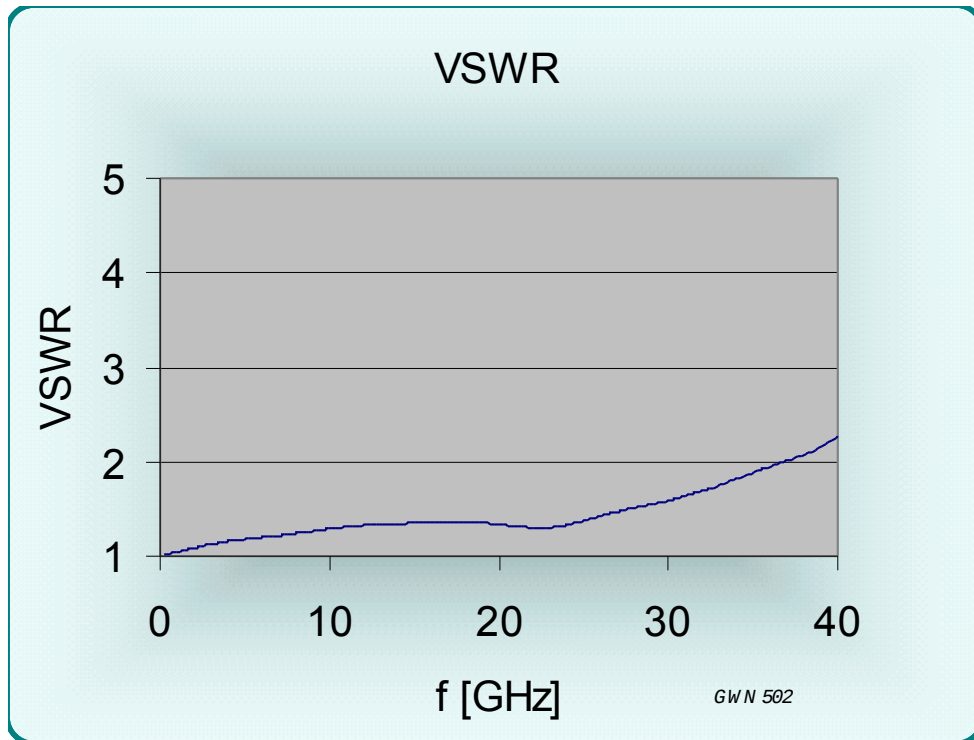


Figure 26 Standing wave ratio VSWR (f) [1 / div.]

The VSWR remains below 2 : 1 to a frequency of 36.7 GHz.

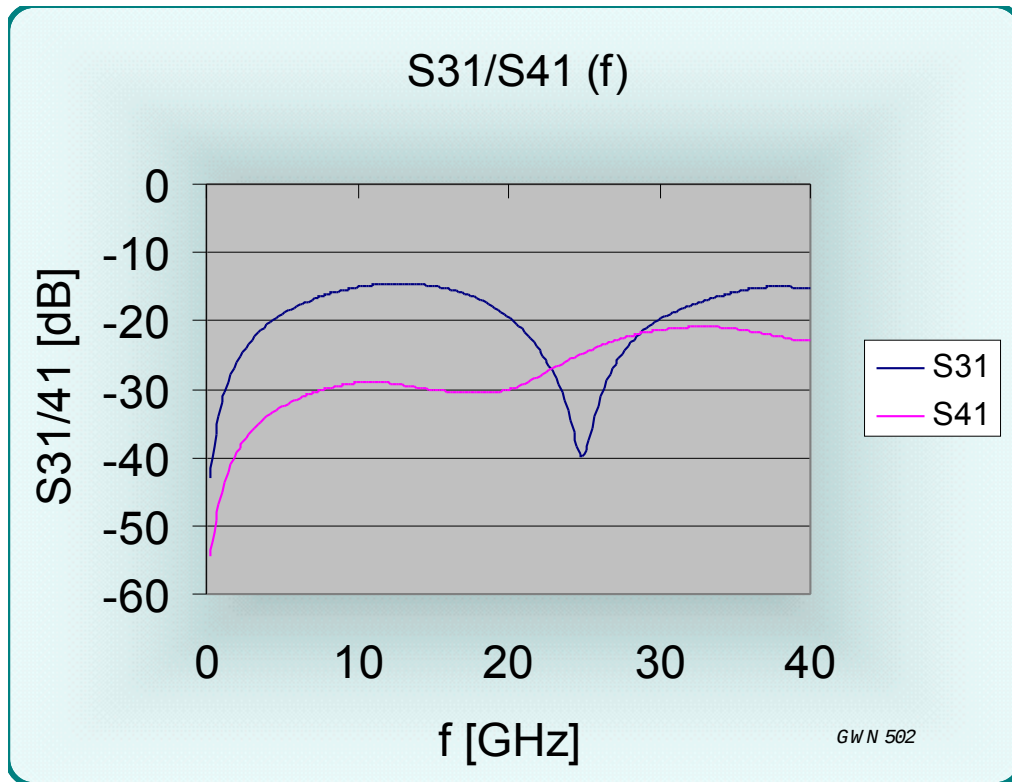


Figure 27 Crosstalk as a function of frequency

The graph shows forward crosstalk from port 1 to port 4 (S41, far end crosstalk {FEXT}) and backward crosstalk from port 1 to the adjacent terminal (port 3, S31, near end crosstalk {NEXT}). The -20 dB point is reached at 4.2 GHz (S31) and not before 40.0 GHz (S41).

For the purpose of model development the open circuit and short circuit backward crosstalk S31 is also recorded. It is shown below for the different sites. Model development yields a mutual capacitance of 0.084, 0.052, 0.044 and 0.016 pF and a mutual inductance of 0.38, 0.30, 0.19 and 0.069 nH for corner, edge field and diagonal sites, respectively.

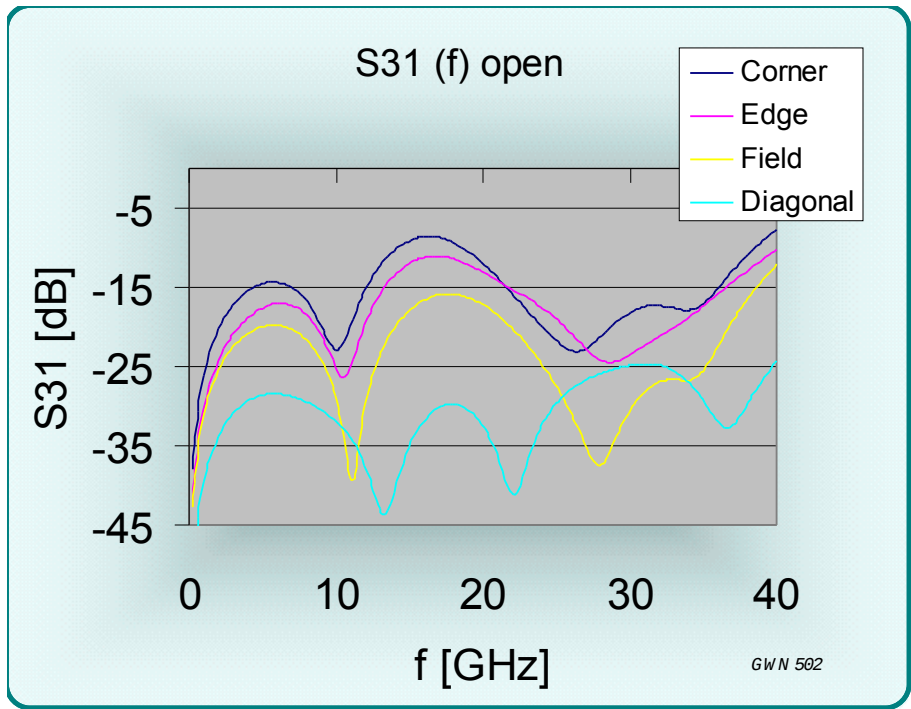


Figure 28 Open circuit crosstalk from port 1 to port 3

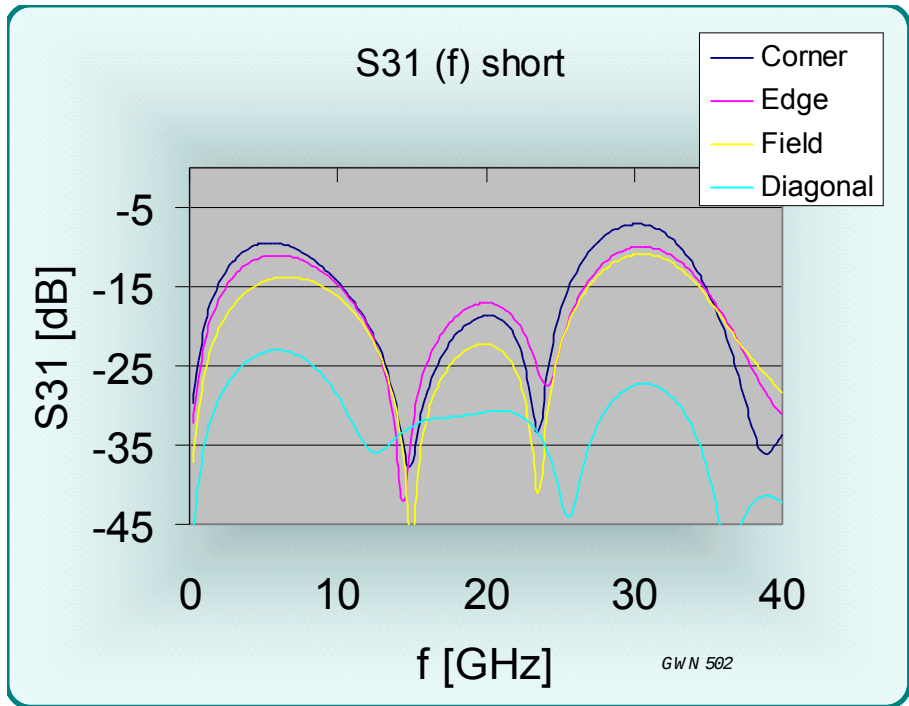


Figure 29 Short circuit crosstalk from port 1 to port 3

SPICE Models

A lumped element SPICE model for the Custom Interconnects Fuzz Button Socket/Interposer in G-S-G configuration is shown below:

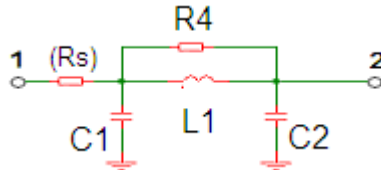


Figure 30 Lumped element SPICE model

The resistance value ($R4$) approximates the loss term encountered. The series resistance R_s is very small and does not significantly impact S-parameters. It can be determined by DC measurements but is not included in this model.

The values for the elements are

Site	$C_g=C1+C2$	$L1$	$R4$
Corner	0.343 pF	1.54 nH	600 Ohms
Edge	0.377 pF	1.36 nH	1000 Ohms
Field	0.392 pF	1.17 nH	700 Ohms
Diagonal	0.392 pF	1.17 nH	700 Ohms

Toward the cutoff frequency of the Pi section the lumped element model becomes invalid. This happens above 10 GHz for the above model. Accuracy of the model is better than 0.5 dB up to 7.8, 7.8 and 8.2 GHz for C,E,F. The second model developed is a transmission line model:

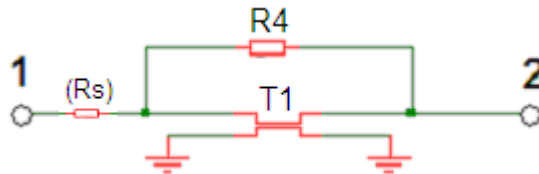


Figure 31 Transmission line model for the Fuzz Button Socket/Interposer

Again, $R4$ describes loss and the series resistance R_s is very small and not included. The array configuration with signal pins surrounded by ground pins provides a transmission line environment with the following parameters:

	Z_0	L	$R4$
Corner	67.0 Ω	23.00 ps	800 Ω
Edge	60.2 Ω	22.67 ps	5000 Ω
Field	54.6 Ω	21.40 ps	5000 Ω

Values computed here are generally lower than those measured by TDR. A possible cause is a more complex equivalent circuit with short sections of low impedance transmission line that cannot be resolved by the limited risetime TDR measurement.

Accuracy for S21 is better than 0.5 dB to 31.7, 32.9 and #N/A GHz for C,E,F.

The lumped model does not remain valid at high frequencies. Alternatives are to split this model into multiple sections with the same total capacitance and inductance or to use a transmission line model. For models that are more accurate at high frequencies it is recommended to use a multi-pole SPICE subcircuit representation or sNp Touchstone S-parameters.

Time domain

The TDR simulation results indicate both capacitive and inductive responses just as observed in the measurement (see TDR THRU).

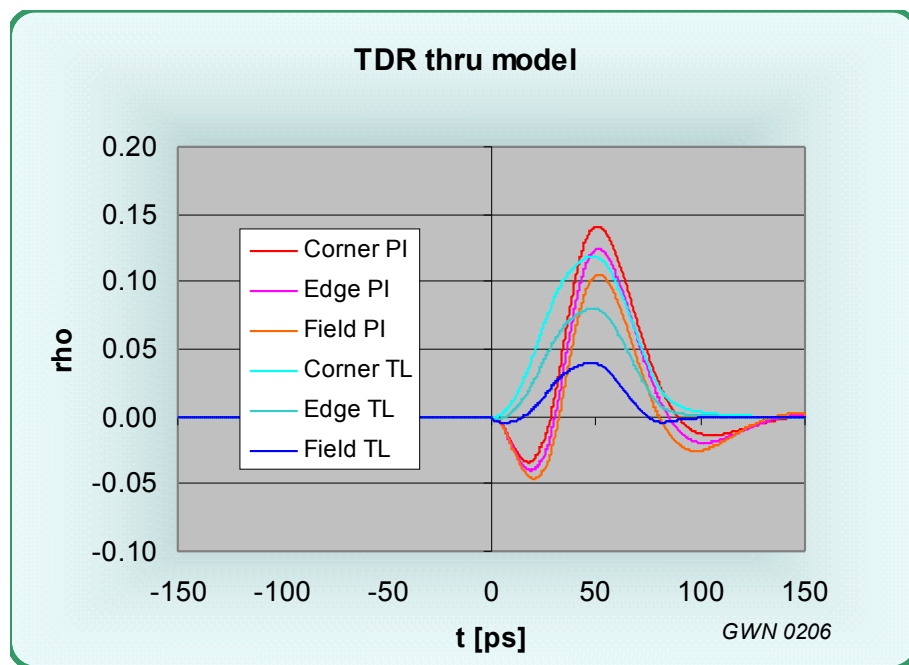


Figure 32 TDR model results

TMline TDR simulation results indicate a response comparable to that observed in measurements (see TDR THRU). However, simple lumped element models do not agree as well for fast risetimes. Just as in the frequency domain for better approximation at higher speeds, a transmission line model, more detailed multi-section LC model or sNp parameters should be used. Since these responses are computed

from the model result, not the TDR result, the previously mentioned different computed impedance values are reflected in a divergent model from the TDR measurement.

Risetime contributions of a signal transmitted through the pin are shown below:

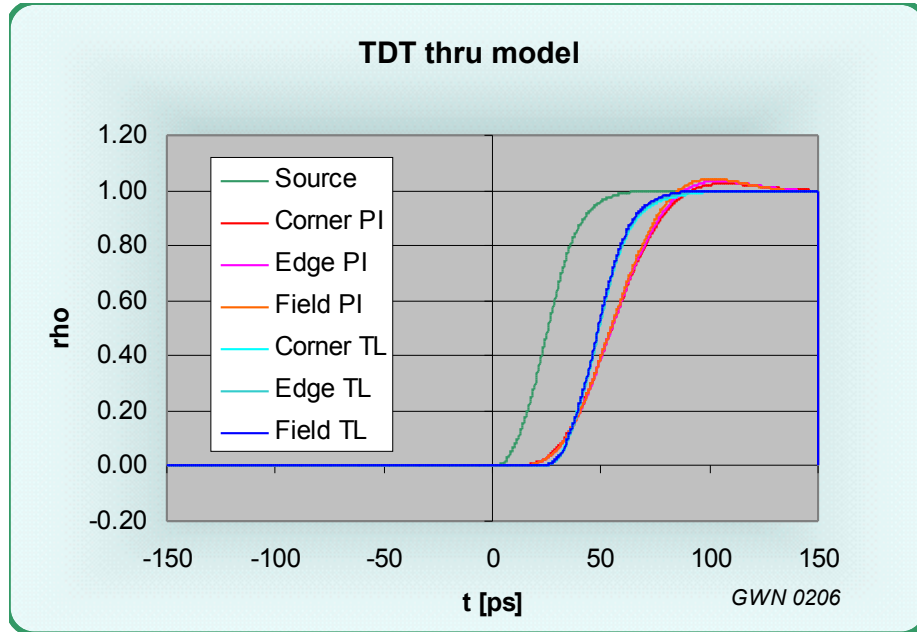


Figure 33 TDT model

Risetimes are comparable to that obtained in the measurement.

Frequency domain

The model's phase responses are also divided into lumped element and transmission line equivalent circuits.

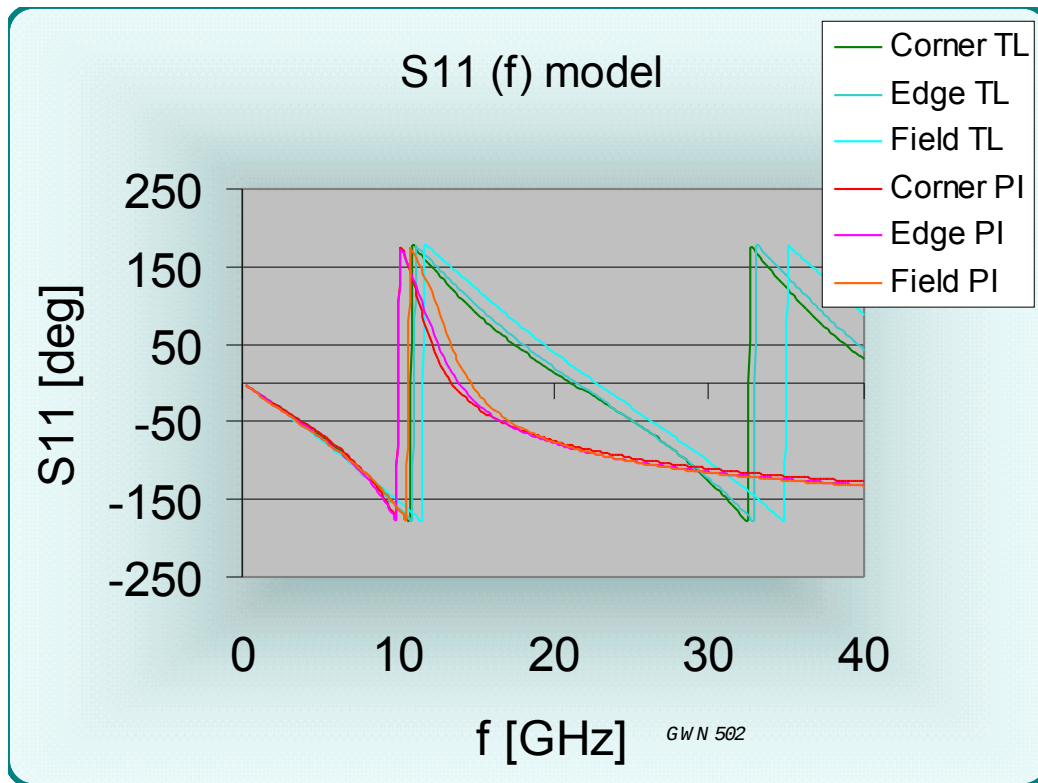


Figure 34 S11 phase (f) for open circuited case

The evolution of phase with frequency is comparable to that measured. The lumped element model has a cutoff frequency of about 10 GHz.

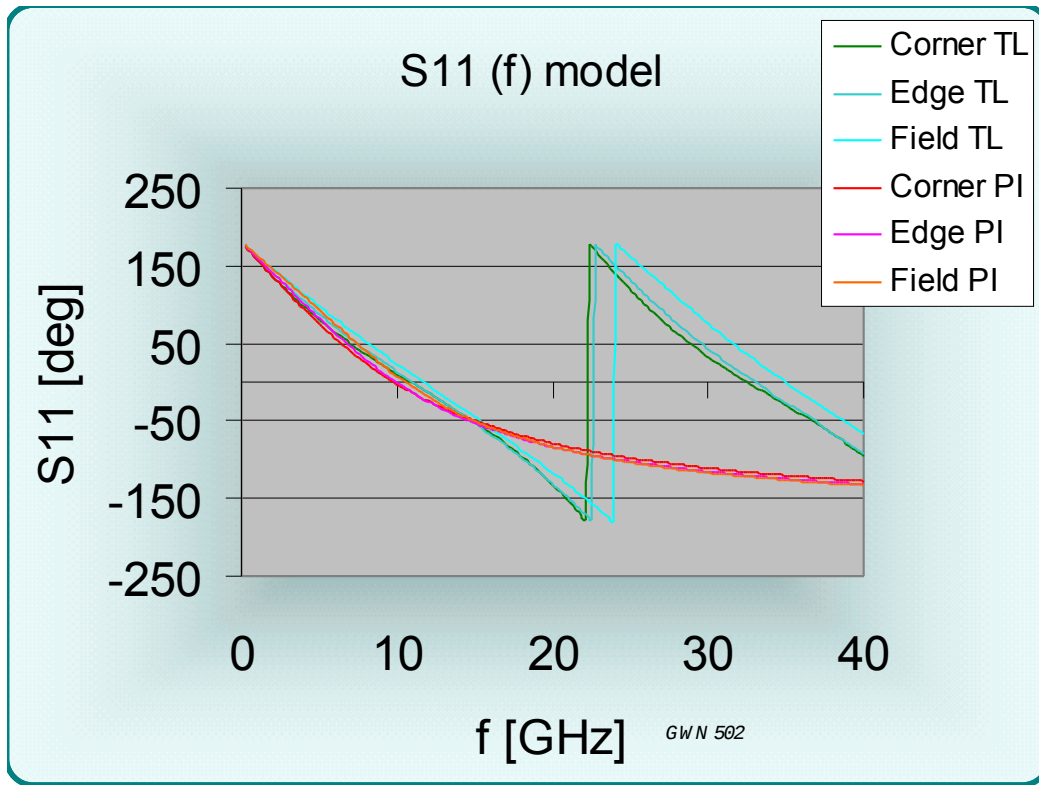


Figure 35 S11 phase response (short circuit)

The short circuit phase evolution with frequency is also comparable to that actually measured.

The insertion loss results below also clearly demonstrate the limits of the lumped element model. As the frequency approaches the cutoff frequency for the Pi section, insertion loss increases significantly. The transmission line model does not suffer from this shortcoming.

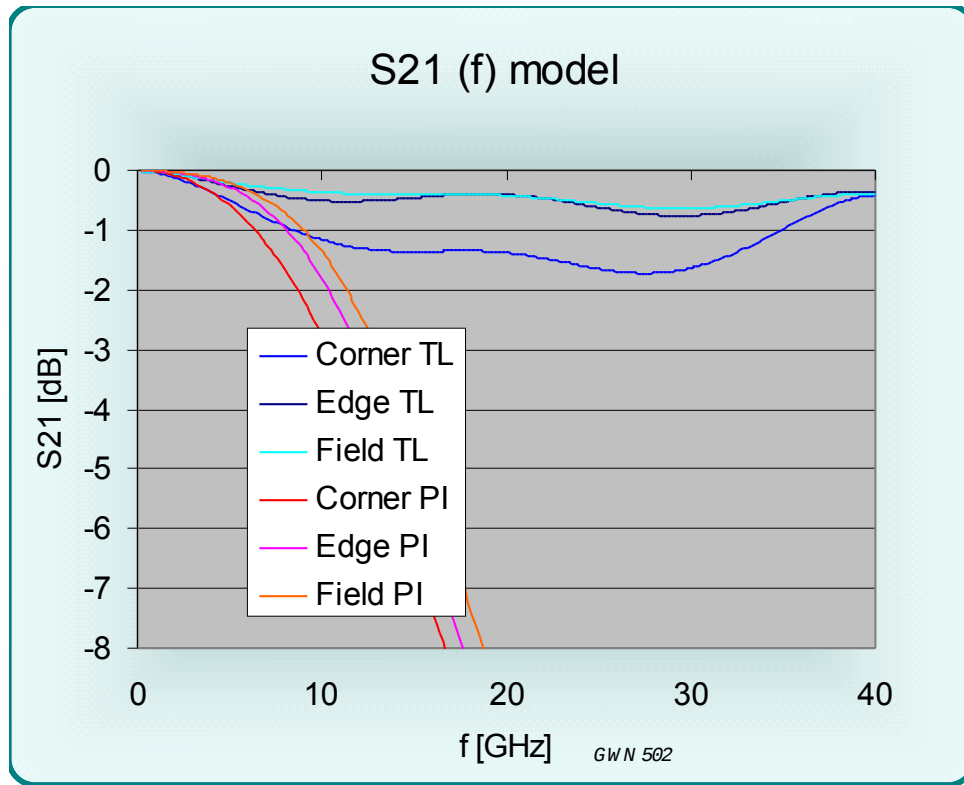


Figure 36 Insertion loss as a function of frequency

The lumped element frequency domain model used for evaluating the mutual elements also consists of the lumped model for the single pin plus a mutual inductance and two coupling capacitors. The model was used in configurations corresponding to the actual measurements. Contact resistance is again omitted because of negligible impact.

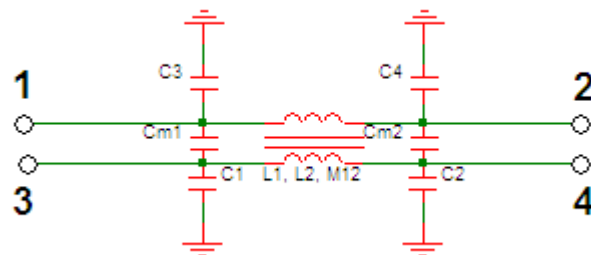


Figure 37 Equivalent circuit for G-S-S-G (mutual coupling)

The limitations for the G-S-S-G models are the identical to the G-S-G version.

The values for this model are:

Site	C1,2,3,4	Cm1,Cm2		L1, L2	M	
Corner	0.172	0.042	pF	1.54	0.384	nH
Edge	0.188	0.026	pF	1.36	0.301	nH
Field	0.196	0.022	pF	1.17	0.193	nH
Diagonal	0.196	0.008	pF	1.17	0.069	nH

The lumped model does not remain valid at high frequencies. Alternatives are a split of the lumped model into multiple sections, e.g. three sections with 1/3 the values for the total capacitance or inductance each or the use of a transmission line model with coupled transmission lines and added loss terms as shown below (field site only):

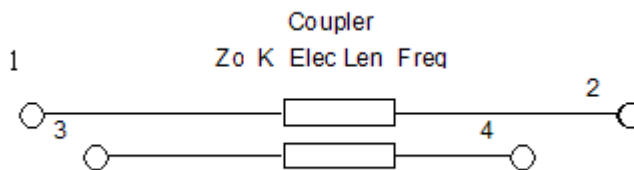


Figure 38 Transmission line equivalent circuit for crosstalk

The model shows two coupled transmission lines with the respective in- and outputs. Its elements are Z_o , L_{el} , k and $f_{(180deg)}$:

Field	55.3	Ω	21.6	ps	0.17	23.4	GHz
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Simulations are performed like the measurements where S31 measures the backward crosstalk (NEXT), while ports 2 and 4 are terminated in 50 Ohms. Likewise, the forward crosstalk S41 (FEXT) is determined with ports 2 and 3 terminated into 50 Ohms.

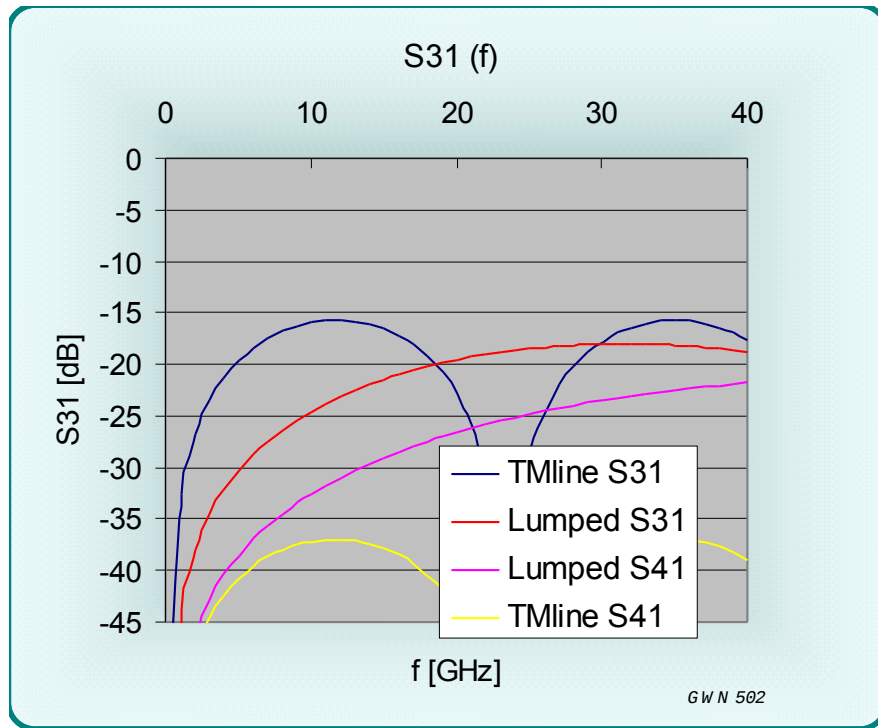


Figure 39 Crosstalk S31 and S41 [dB] as a function of frequency

The TM line model for S41 underestimates crosstalk. This is of little consequence, however, since the overall level of forward crosstalk is low to begin with. Again, model limit frequencies as noted in the G-S-G case apply. For fully accurate representations Touchstone parameters (SnP) or optional multi-pole representations should be used.

Summary sheet

Custom Interconnects

Fuzz Button with Hardhat Test Socket/Interposer

1.00 mm pitch

12/14/2015

Measurement results:

	Corner	Edge	Field	
Delay	23.9	23.1	21.6	ps
Risetime open	52.5	43.5	33	ps
Risetime short	88.5	111	52.5	ps
Risetime thru, 50Ω	40.5	31.5	30	ps
Insertion loss (1dB)	7.6	31.9	>40	GHz
Insertion loss (3dB)	37.5	>40	>40	GHz
VSWR (2:1)	37.5	33.9	>40	GHz

PI equivalent circuit component values:

Site	Cg=C1+C2		L1		R4	
Corner	0.343	pF	1.54	nH	600	Ohms
Edge	0.377	pF	1.36	nH	1000	Ohms
Field	0.392	pF	1.17	nH	700	Ohms
Diagonal	0.392	pF	1.17	nH	700	Ohms

It should be noted that there are 2 capacitors in the PI equivalent circuit. Each of them has half the value listed here. R4 is not the series resistance (Cres) but in parallel with L1; please see report for explanation.

Mutual component values:

Site	Cm		M	
Corner	0.084	pF	0.384	nH
Edge	0.052	pF	0.301	nH
Field	0.044	pF	0.193	nH
Diagonal	0.016	pF	0.069	nH

It should be noted that there are 2 capacitors in the PI equivalent circuit. Each of them has half the value listed here.

Transmission line equivalent circuit values:

Site	Zo		td	
Corner	67.1	Ω	23.9	ps
Edge	59.3	Ω	23.1	ps
Field	55.3	Ω	21.6	ps

The impedance listed is that observed in the time domain measurements. It is different than that calculated from the measured L,C parameters because of the limited time domain signal risetime.